# **SURFBOARDS®**

THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TAM



## 33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33518

33518

8 LEAD .5 mm PITCH DEVICES

**DEVICE LEAD WIDTH 1.5, To Max 3.0 MM** 

**ACCEPTS** 

ANALOG

E-8-1 PKG

PARTIAL LISTING

**FAIRCHILD** 

8LD, MICROPAK 1.6MM SQ.

ON SEMI

ULLGA8 1.5x1.5,0.5P UQFN8 1.5x1.5.0.5P

UQFN8 1.6x1.6,0.5P

TEXAS INST. RSE (S-PQFP-N8) UQFN

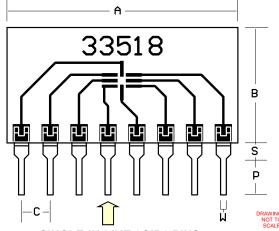
**RUG (S-PQFP-N8)** 

#### ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

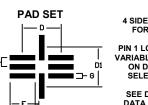
Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

> **JUST ADD PARTS** AND



SINGLE-IN-LINE (SIP) PINS ON .100 in. CENTERS



**4 SIDED LEAD** FORMAT.

PIN 1 I OCATION VARIABLE BASED ON DEVICE SELECTED.

> SEE DEVICE DATA SHEET.

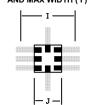


MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING. SEE WEBSITE FOR SOLDERING SUGGESTIONS

### **BOARD SPECIFICATIONS**

BOARD MATERIAL: .8mm, +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.

CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +- .5mm .020in.



RoHS

PLUG-IN ™ FIG. MM NOTE: 20.32 .800 BOARD WIDTH +- .5mm .020in. R 10.16 400 BOARD HEIGHT +-.5mm .020in. 2.54 .100 SIP PIN SPACE +-.20mm .008in. D. D1 2.1 .083 PAD CENTERLINE .5 020 **DEVICE LEAD PITCH** 1.4 055 PAD LENGTH G 3 012 PAD WIDTH Н .2 .008 3.0 118 MAX LEAD WIDTH 1.5 .059 TYPICAL LEAD WIDTH .130 LENGTH FROM SHOULDER +-.5mm .020in. 1 57 062 PIN SHOULDER HEGHT s .5 .020 PIN WIDTH

TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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